

Customer Approval:

□ Accept

SPECIFICATION FOR LCD MODULE

MODULE NO: YB-TG1024600S11A-C-A0

Doc.Version:02

			I
YEEBO	NAME	SIGNATURE	DATE
Prepare	Mechanical Engineer	王周雄	2020-08-14
Check	Electronic Engineer		
Verify			
Approval			

□ APPROVAL FOR SPECIFICATIONS ONLY

■ APPROVAL FOR SPECIFICATIONS AND SAMPLE

WIMRD005-02-D

□ Reject

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1. Revision History

CHANGED BY	DESCRIPTION		DATE	DOC. Version	Sample Version
W.Z.X	First issue	SPEC ONLY	2020-06-05	00	A0
W.Z.X	Update brightness, number of lights	SPEC ONLY	2020-07-21	01	A0
W.Z.X	First sample	FULL SPEC	2020-08-14	02	A0

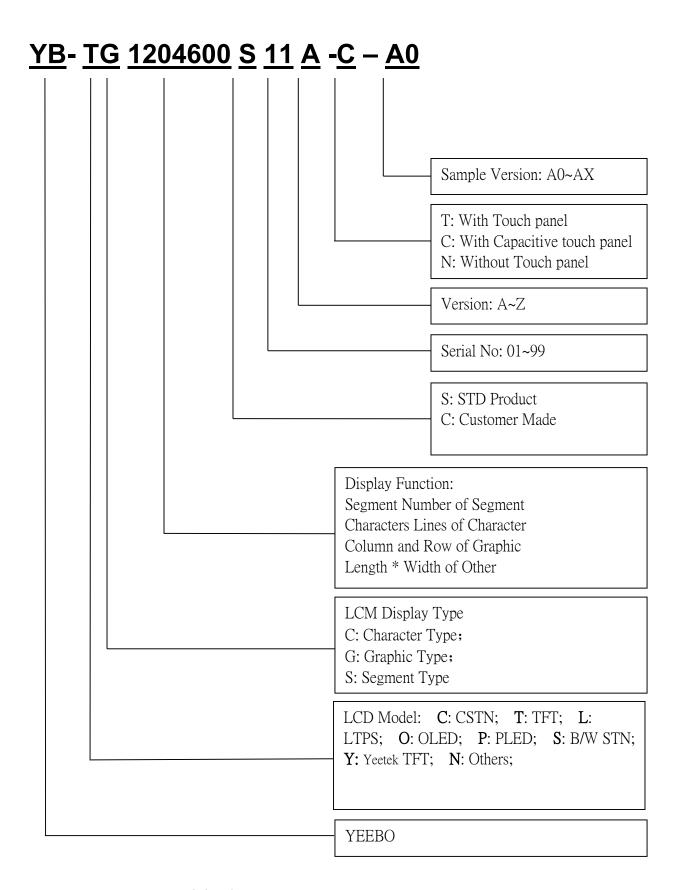


2. Table of Contents:

NO	CONTENTS	PAGE
1	Revision History	1
2	Table of Contents	2
3	Module Numbering System	3
4	General Specification	4
5	LCM drawing	5
6	Electrical Characteristics	6
7	Optical Characteristics	13
8	Interface Pin Assignment	15
9	Block Diagram	17
10	Block diagram	18
11	Standard Specification for Reliability	19
12	Specification of Quality Assurance	21
13	Handing Precaution	29
14	Warranty	29
15	Guarantee	30



3. Module Numbering System:



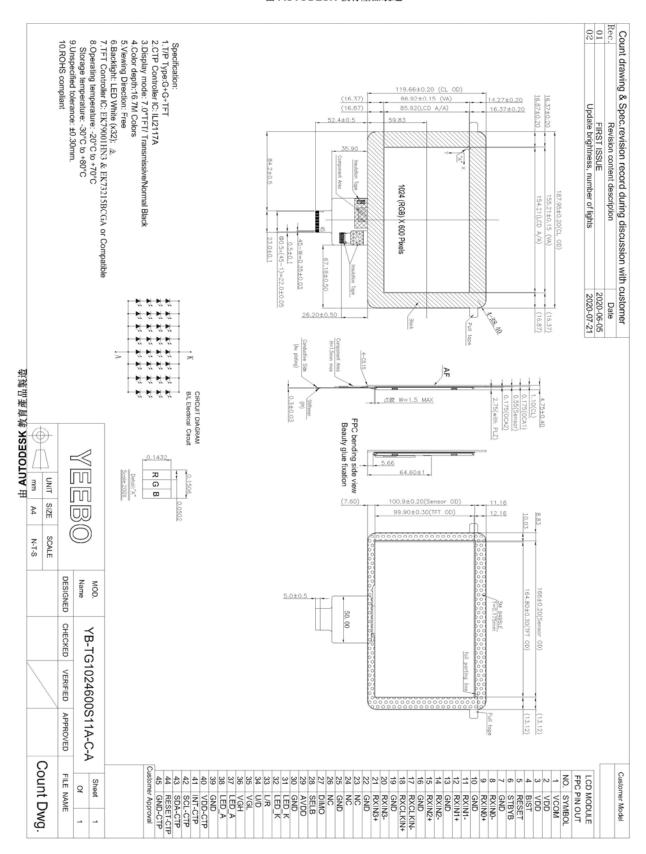


4. General Specification:

ITEM	CONTENTS
Module Size	187.95(W) * 119.66(H) * 4.75(T) mm
Display Size(Diagonal)	7inch
Display Format	1024(RGB)* 600 Pixels
Pixel Pitch	0.1506 (H)mm*0.1432(V) mm
LCD Type	TFT(16.7M)/ Transmissive/Normal Black
Active Area	154.21(W)*85.92(H)mm
View Angle	Free
Drive IC	EK79001HN3 & EK73215BCGA
CTP IC	ILI2117A
Weight(g)	≈192. 84g
Fireware	8819_130k_v1.6.bin
Test Configuration	autoSettings.ini

5. LCM drawing:

由 AUTODESK 教育產品製造



盐媒品重育獎 AS3GOTUA 由



6. Electrical Characteristics

6-1 Absolute Maximum Ratings

6-1-1 TFT Absolute Maximum Ratings (Ta=25°C VSS=0V)

Item	Symbol	Min.	Type	Max.	Unit	Remark
Dowar Supply voltage	VDD	-0.5	ı	5.0	Volt	
Power Supply voltage	AVDD	-0.5	ı	15.0	Volt	
Operating Temperature	Topr	-20	-	+70	$^{\circ}$ C	
Storage Temperature	Tstg	-30	-	+80	$^{\circ}$ C	

Note1: Absolute maximum rating is the limit value beyond which the IC maybe broken.

6-2 Operating Conditions

6-2-1 TFT Operating Conditions

(Ta=25°℃)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
	VDD	-	2.3	3.3	3.6	Volt
Dayyar Supply valtage	AVDD	-	9.4	9.6	9.8	Volt
Power Supply voltage	VGH	-	16	18	20	Volt
	VGL	-	-7	-6	-5	Volt
Input Voltage	VCOM		1	3.2	4	Volt
Power Supply Current for	IVDD	DVDD=3.3V	-	22.61	33.92	mA
Driver	IAVDD	AVDD=9.6V	-	16.46	24.69	mA

6-2-2 TP Operating Conditions

 $(Ta=25^{\circ}C)$



Table 5-2: Power Supply

Item	Symbol	Min	Тур.	Max	Unit
System power supply voltage	VDD	2.8	V 7	3.3	V
Ambient operating temperature	TA	-40	7	85	°C
Junction Temperature	Tj		7	125	°C

Table 5-3: DC Characteristics (Topr = 25°C)

Item	Symbol	Min	Тур.	Max	Unit
Input Voltage, High 1	(V _{IH1}) ¹	1			V
Input Voltage, High 2	(V _{IH2}) ²	1.3			V
Input Voltage, Low	(V _{IL})			0.5	V
Output Voltage, High 1	(V _{OH1}) ³		See Note3		V
Output Voltage, High 2	(V _{OH2}) ⁴	V _{VDD} - 0.1			V
Output Voltage, Low	(V _{OL})			0.1	V

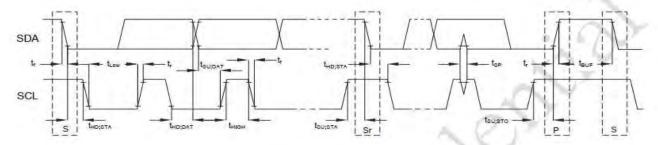
Specifications are subjected to change without notice.

Notes:

- 1. V_{IH1} includes pins CHIP_EN, SDA, SCL, INT
- 2. V IH2 includes pin EXT_CLK
- 3. V_{OH1} is for INT output voltage level which is programmable by registers. Typical values are 1.2V/1.5V/1.8V/V_{VDD}.
- 4. V_{OH2} refers to other digital pins.

6-3 Timing Characteristics

6-3-1 TP I²C interface



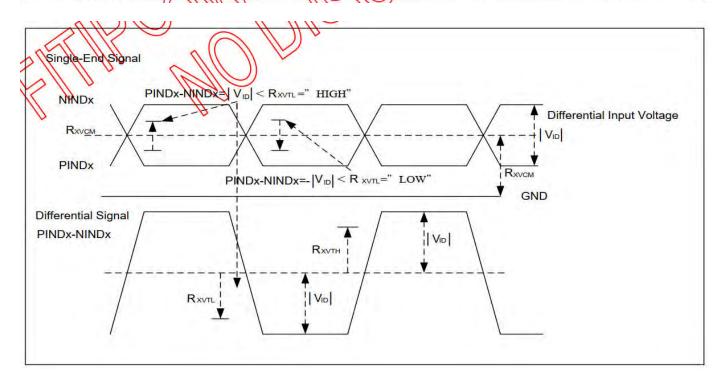
Symbol	Parameter		100KHz		400KHz			
Symbol	Parameter	Min	Max	Unit	Min	Max	Unit	
f _{SCL}	SCL clock frequency	0	100	kHz	0	400	KHz	
t _{HD;STA}	Hold time (repeated) START condition. After this period, the first clock pulse is generated	4.0	-	μs	0.6	T- y ,	μs	
t _{LOW}	LOW period of the SCL clock	4.7	=	μs	1.3	201	μs	
t _{HIGH}	HIGH period of the SCL clock	4.0	-	μs	0.6	-	μs	
t _{SU;STA}	Set-up time for a repeated START condition	4.7	1-	μs	0.6		μs	
t _{HD;DAT}	Data hold time	0	3.45	μs	0	0.9	μs	
t _{SU;DAT}	Data set-up time	250	-	ns	100		ns	
tr	Rise time of both SDA and SCL signals	-	1000	ns	T	300	ns	
t _f	Fall time of both SDA and SCL signals	T07	300	ns		300	ns	
t _{SU;STO}	Set-up time for STOP condition	4.0	-	μs	0.6	1.40	μs	
t _{BUF}	Bus free time between a STOP and START condition	4.7	4	μs	1.3	-	μs	

6-3-2 TFT Timing Characteristics



LVDS DC characteristic

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Differential input high threshold voltage	RxVTH			+0.1V	V	RxVCM=1.2V
Differential input low threshold voltage	RxVTL	-0.1				
Input voltage range(single-end)	RxVIN	0		2.4	2	
Differential input common mode voltage	RxVCM	V _{ID} /2		2.4 - V _{ID} /2	Malin	
Differential input voltage	V _{ID}	0.2	05	7 6	\ \ \	
Differential input leakage current	RxVтн	-10		1 +yo		
LVDS Digital Operating Current	Iddlvsd		40(TBD)	567	∭ mA	Fclk=65Mhz, VDD=3.3V
LVDS Digital Standby Current	Istlvds	Flan	10(TBB)	50	uA	Clock & all functions are stop

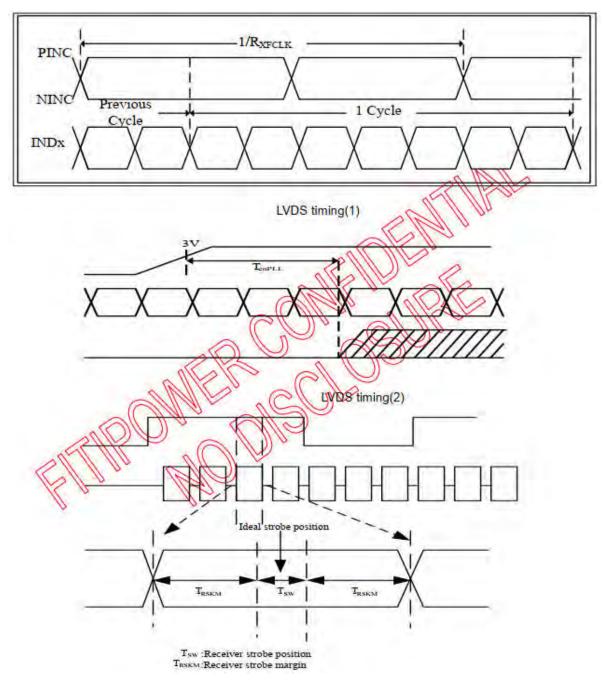




6-3-3 AC Electrical Characteristics

LVDS mode

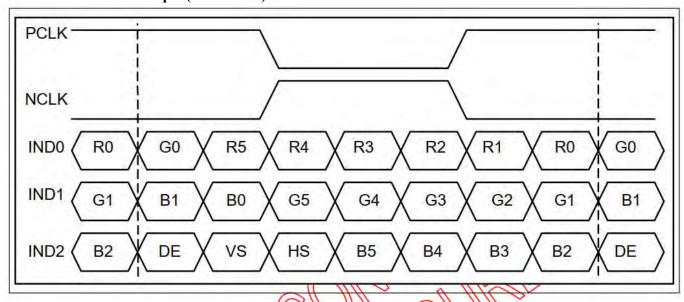
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Clock Frequency	RXFCLK		20	-	71	MHz
Input data skew margin	TRSKM	WipL=400mV RxVcm=1.2V RxFCLK=71MHz	500			ps
Clock High Time	MANCH			4/(7* RxFCLK)		ns
Clock right like	Marie			4/(/ TXPCER)		ns
Clock Low Time	TLVCL			3/(7* RxFCLK)		ns
PLL wake-up-time	TenPLL				150	us



Module P/N: YB-TG1024600S11A-C-A0

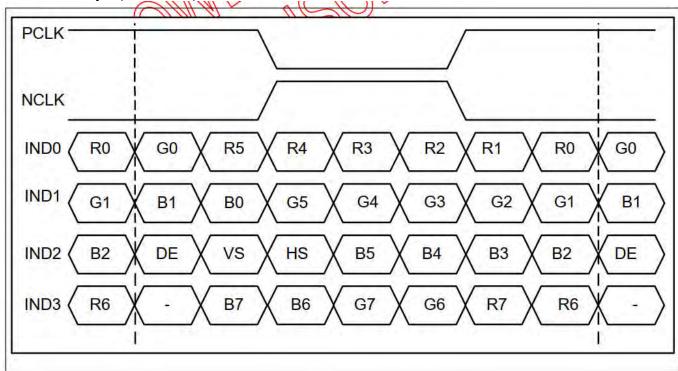


6-3-4 Data Input Format for LVDS 6-bit LVDS input(HSD="H")



6-bit LVDS Input Timing chart

8-bit LVDS input(HSD="L")

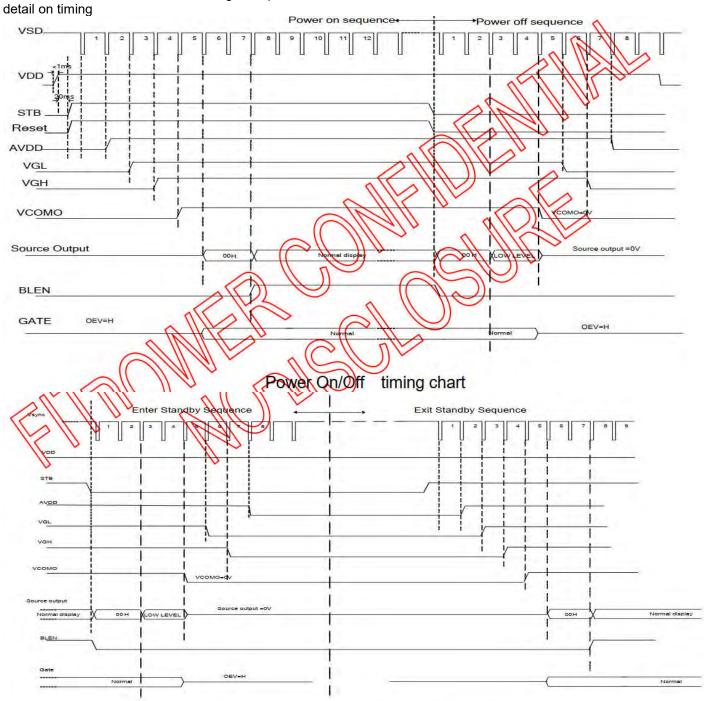


8-bit LVDS Input Timing chart



6-3-5 Power On/Off Sequence

In order to prevent IC from power on reset fail, the rising time (TPOR) of the digital power supply VDD should be maintained within the given specifications. Refer to "AC Characteristics" for more detail on timing

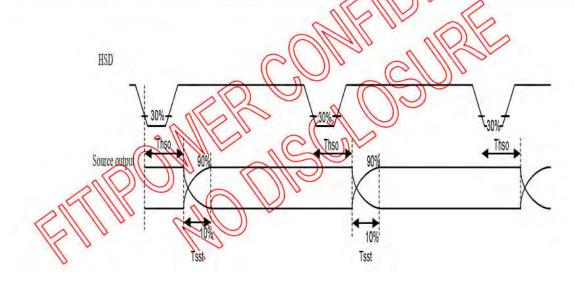


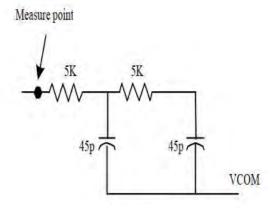
Enter and Exit Standby Mode timing chart



6-3-6 Output Timing Table Output Timing Table

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
DCLK frequency	Fclk	-	65	71	MHz	VDD =2.3~3.6V
DCLK cycle time	Tclk	14.1	15.4		ns	
DCLK pulse duty	Tcwh	40	50	60	%	Tclk
Time from HSD to Source Output	Thso		64	1.9.1.	DCLK	
Time from HSD to LD	Thld	1.3	64	14.30	DCLK	
Time from HSD to STV	Thstv		2	1, 3=1	DCLK	2 Il Ma
Time from HSD to CKV	Thckv	-	20	[E#1]	DCLK	11 12/12
Time from HSD to OEV	Thoev	-	4	-	DC/K	
LD pulse width	Twld	-	10	-/	DELK	11 2
CKV pulse width	Twckv	-	66	77-	DOLK	7
OEV pulse width	Twoev		74	(-)	DCNK	





Source Output Timing



7. Optical Characteristics:

Item S		Crymah al	hal Canditions		Specifications			Note
Item		Symbol	Conditions	Min	Тур	Max	Unit	Note
Transmitt (With F		T(%)	-	4.8	5.0	ı	ı	-
Contrast	Ratio	CR	Θ=0 Normal Viewing Angle	500	800	1	1	(1) (2)
Response	Time	TR+TF	-	-	25	40	ms	(1)(3)
	Hor	Өх+		-	85	ı	deg.	
Viewing	ПОІ	Өх-	CR≧10	-	85	ı		
angle	Ver	⊖y+	CK=10	-	85	-		-
	vei	Өу-		_	85	-		

Measuring Condition

1. Measuring surrounding: dark room

2. Ambient temperature: 25±2°C

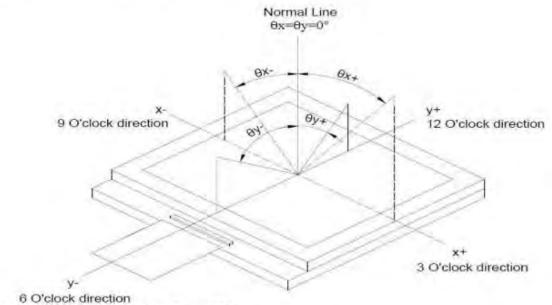
3. 30 min. Warm-up time.

Color of CIE Coordinate:

Item		Symbol	Condition	Min.	Тур.	Max.
	D 1	X		0.556	0.606	0.656
	Red	y		0.293	0.343	0.393
	Green	X		0.295	0.345	0.395
Chromaticity		у	$\theta = \phi = 0 \circ$	0.526	0.576	0.626
Coordinates	Blue	X	LED Backlight	0.100	0.150	0.200
(Transmissive)		У		0.058	0.108	0.158
	White	X		0.273	0.323	0.373
		у		0.302	0.352	0.402



Note (1) Definition of Viewing Angle:

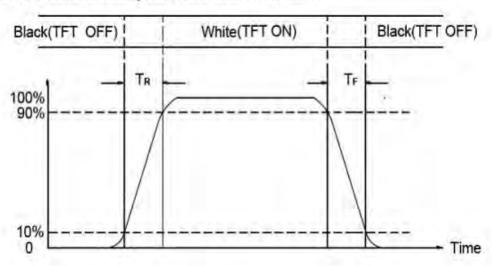


Note (2) Definition of Contrast Ratio(CR): measured at the center point of panel

Contrast ratio (CR)= Photo detector output when LCD is at "White" state

Photo detector output when LCD is at "Black

Note (3) Definition of Response Time: Sum of TR and TF





8. Interface Pin Assignment: 8-1 LCM FPC Interface

No.	Symbol	Function
1	VCOM	Common Voltage
2	VDD	Power Voltage
3	VDD	Power Voltage
4	BIST	Normal Operation/BIST pattern select. Normally pull low BIST = H : BIST(DCLK input is not needed) BIST = L : Normal Operation
5	RESET	Global reset pin. Active Low to enter Reset State. Normally pull high.
6	STBYB	Standby mode & Normally pulled high. STBYB = "1", normal operation STBYB = "0", timing controller, source driver will turn off, all output are High-Z
7	GND	Power Ground
8	RXIN0-	-LVDS differential data input
9	RXIN0+	+LVDS differential data input
10	GND	Power Ground
11	RXIN1-	-LVDS differential data input
12	RXIN1+	+LVDS differential data input
13	GND	Power Ground
14	RXIN2-	-LVDS differential data input
15	RXIN2+	+LVDS differential data input
16	GND	Power Ground
17	RXCLKIN-	-LVDS differential clock input
18	RXCLKIN+	+LVDS differential clock input
19	GND	Power Ground
20	RXIN3-	-LVDS differential data input
21	RXIN3+	+LVDS differential data input
22	GND	Power Ground
23	NC	No Connect
24	NC	No Connect
25	GND	Power Ground
26	NC	No Connect
27	DIMO	Backlight dimmer signal for external controller. DIMO = "0", Turn off external backlight controller DIMO = "1", Logical control signal to turn on external backlight controller
28	SELB	6 bit/8 bit mode select Note1



29	AVDD	Power for Analog Circuit
30	GND	Power Ground
31	LED_K	LED Cathode
32	LED_K	LED Cathode
33	L/R	Horizontal inversion Note2
34	U/D	Vertical inversion Note2
35	VGL	Gate OFF Voltage
36	VGH	Gate on Voltage
37	LED_A	LED Anode
38	LED_A	LED Anode
39	GND	Power Ground
40	VDD-CTP	Voltage for digital circuit
41	INT-CTP	Indicate coordinate data ready
42	SCL-CTP	I2C Serial Clock Power
43	SDA-CTP	I2C Serial Data
44	RESET-CTP	System reset signal input, active low
45	GND-CTP	Power Ground

Note1: If LVDS input data is 6 bits ,SELB must be set to High;

If LVDS input data is 8 bits ,SELB must be set to Low.

Note2: When L/R="0", set right to left scan direction.

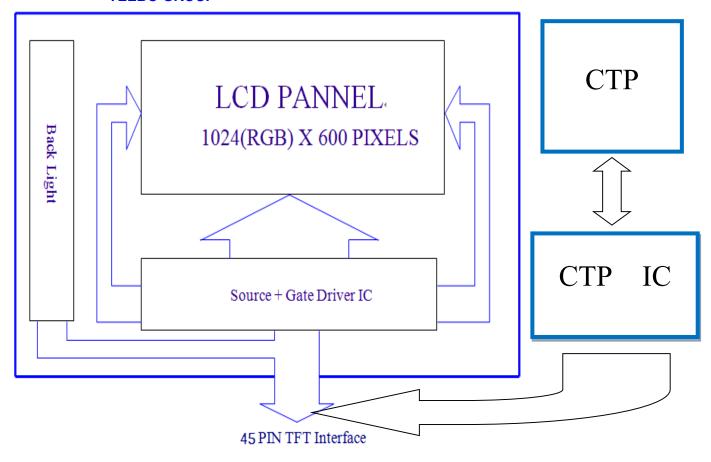
When L/R="1", set left to right scan direction.

When U/D="0", set top to bottom scan direction.

When U/D="1", set bottom to top scan direction.

9.Block Diagram:





10. Backlight:

1. Standard Lamp Styles (Edge Lighting Type):

Module P/N: YB-TG1024600S11A-C-A0

17



The LED chips are distributed over the edge light area of the illumination unit, which gives the less power consumption:

- 2. The Main Advantages of the LED Backlight are as following:
 - 2.1 The brightness of the backlight can simply be adjusted. By a resistor or a potentiometer.

3. Data About LED Backlight:

 $(Ta=25^{\circ}C)$

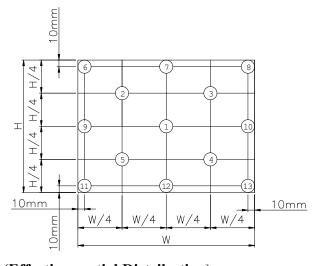
PARAMETER	Sym.	Min.	Тур.	Max.	Unit	Test Condition	Note
Supply Current	I	-	160	-	mA		
Voltage of the Backlight	V_{BL}	10.8	12.4	14.0	V		
Luminous Intensity for LCM	IV	510	600	-	cd/m ²	If=160mA	2
Uniformity for LCM	-	70	-	-	%	11-100IIIA	3
LED Life Time	-	20000	-	-	Hr		4
Color				Wh	ite		

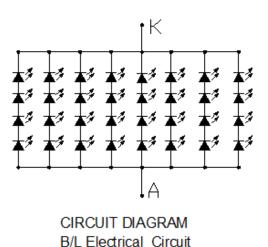
NOTE:

- 1. Backlight Only
- 2. Average Luminous Intensity of P1-P13
- 3. Uniformity = Min/Max * 100%
- 4. LED life time defined as follows: The final brightness is at 50% of original brightness

Measured Method: (X*Y: Light Area)

Internal Circuit Diagram





(Effective spatial Distribution)

Using aperture of 1°, distance 50cm.



11. Standard Specification for Reliability: 11–1. Standard Specifications for Reliability of LCD Module

No	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60°C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles: -30° C for 30 minutes \rightarrow normal temperature for 5 minutes \rightarrow +80°C for 30 minutes \rightarrow normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range: 10Hz ~ 55Hz Amplitude of vibration: 1.5mm X,Y,Z 2 hours for each direction. Sweep time: 12 min
08	Packing drop test	According to ISTA 1A 2001.

^{*}Sample size for each test item is 3~5pcs



11 - 2. Testing Conditions and Inspection Criteria

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in Table 11.2, Standard specifications for Reliability have been executed in order to ensure stability.

No	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

11-3. MTBF

Functions, performance, appearance, etc. shall be free from remar deterioration within 50,000 hours under ordinary operating and st conditions room temperature (25±5°C), normal humidity (50±10% and in area not exposed to direct sun light.	orage
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12. Specification of Quality Assurance:

12-1. Pupose

This standard for Quality Assurance should affirm the quality of LCD module products to supply to purchaser by YEEBO CORPORATION (Supplier).

- 12-2. Standard for Quality Test
 - a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

b. Electro-Optical Characteristics:

According to the individual specification to test the product.

c. Test of Appearance Characteristics:

According to the individual specification to test the product.

d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

e. Delivery Test:

Before delivering, the supplier should take the delivery test.

- (i) Test method: According to MIL-STD105E.General Inspection Level

 take a single time.
- (ii) The defects classify of AQL as following:

Major defect: AQL = 0.65% Minor defect: AQL = 2.5% Total defects: AQL = 2.5%

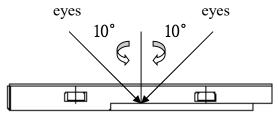
- 12-3. Non- conforming Analysis & Deal With Manners
 - a. Non-conforming Analysis:
 - (i) Purchaser should supply the detail data of non- conforming sample and the non-conforming.
 - (ii) After accepting the detail data from purchaser, the analysis of non- conforming should be finished in two weeks.
 - (iii) If supplier can not finish analysis on time, must announce purchaser before 3 days.
 - b. Disposition of non- conforming:
 - (i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.
 - (ii) Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.
- 12-4. Agreement items

Both sides should discuss together when the following problems happen.

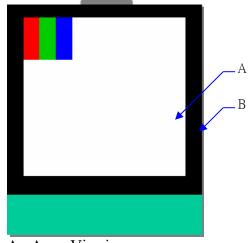
- a. There is any problem of standard of quality assurance, and both sides should think that must be modified.
- b. There is any argument item which does not record in the standard of quality assurance.
- c. Any other special problem.



- 12-5. Standard of The Product Appearance Test
 - a. Manner of appearance test:
 - (i) The test must be under $20W \times 2$ or 40W fluorescent light, and the distance of view must be at 30 ± 5 cm.
 - (ii) When test the model of transmissive product must add the reflective plate.
 - (iii)The test direction is base on around 10° of vertical line.
 - (iiii)Temperature: 25±5°C Humidity: 60±10%RH



(iv) Definition of area:



- A. Area: Viewing area.
- B. Area: Out of viewing area. (Outside viewing area)

b. Basic principle:

- (i) It will accord to the AQL when the standard can not be described.
- (ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.
- (iii) Must add new item on time when it is necessary.
- c. Standard of inspection: (Unit: mm)

12-6. Inspection specification Defect out of viewing area can be neglected.



NO	Item	GROUP		Criterion			AOI
NU	nem	1.1 Missing vertical, hori		l segment,	segment co	ontrast defect.	AQL
01	Electrical Testing	1.2 Missing character, do 1.3 Display malfunction. 1.4 No function or no dis 1.5 Current consumption 1.6 LCD viewing angle of 1.7 Mixed product types. 1.8 Flicker	splay. exceedefect.	eds produc	t specificat	ions.	0.65
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	 2.1 White and black or color spots on display ≤ 0.25mm, no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm. 2.3 Not visible through 5% ND filter 				2.5	
	LCD and	3.1 Round type: As follo Φ = (X+Y) / 2 X Y Y * Densely spaced: No me than two spots within 3 me	nore	Size(0.25< 0.5< 0.8<	(mm) 0. 25 D≤0. 5 D≤0. 8 D≤1. 5 1. 5	Acceptable Q'ty ignored (No more than five spots within 5mm) 3 2 1 NG	2.5
03	Touch Panel black spots, white spots, contamination		Leng ≤ 0.05< W⟩	rawing) th(mm) 0. 05 W < 0. 25 0. 25	Width(mm) ≪6		2.5

NO	Item	Criterion	AQL
04	Polarizer		2.5



	bubbles	If bubbles are visible,				
		judge using black spot	Size Φ(mm)	Acceptable Q'ty	Area	
		specifications, not easy	$\Phi \leq 0.15$	Accept no dense	V.A	
		to find, must check in specify direction	$0.15 < \Phi \le 0.3$	3	V.A	
		specify direction	$0.30 < \Phi \le 0.5$	1	V.A	
			0.50< Φ≤1	2	Out of	
					V.A	
0.5	G 4 1	F 11 NO 2 2 L' T	1<Ф	0	-	
05	Scratches Mura	Follow NO.3 -2 Line Type		.,		2.5
00	Iviura	Not visible through 5% N Symbols:	D filter in 50% gra	y.		2.5
07	Chipped glass	x: Chip length y: Cook: Seal width t: Cook: Cook: Seal width t: Cook: Seal width t: Cook: Seal width to the cook: Seal width to the cook: Seal width time time time time time time time time	hip width ot over viewing area fot exceed 1/3k hips, x is the total 1 hip width ot over viewing area fot exceed 1/3k	LCD side length en panels: x : Chip length $x \le 1/8a$ $x \le 1/8a$ ength of each chip $x \le 1/8a$ $x \le 1/8a$ $x \le 1/8a$		2.5

ſ	NO	Itam	Criterion	ΛΩΙ
	NO	nem	Criterion	AQL



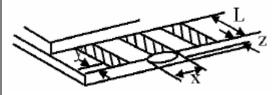
Symbols:

x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length

L: Electrode pad length

7.2 Protrusion over terminal:

7.2.1 Chip on electrode pad:

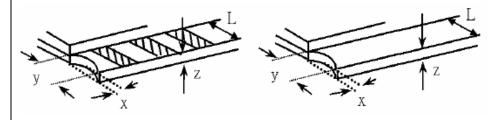


y: Chip width	x: Chip length	z: Chip thickness	
y≦0.5mm	x≤1/8a	0< z≦t	

7.2.2

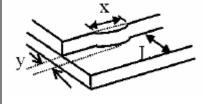
Non-conductive portion:

08 Glass crack



y: Chip width	x: Chip length	z: Chip thickness	
$y \leq L$	$x \leq 1/8a$	0< z≦t	

- ⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.
- ① If the product will be heat sealed by the customer, the alignment mark must mot be damaged.
- 7.2.3 Substrate protuberance and internal crack



y: width	x: length
$y \le 1/3L$	$X \leq a$

NO	Item	Criterion	AQL

2.5



09	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
10	Backlight elements	 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. 	2.5 2.5 0.65
11	Bezel	Bezel must comply with product specifications.	2.5
12	PCB、COB	 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. 	2.5 2.5 2.5 2.5 0.65
13	FPC	12.1 FPC terminal damage \leq 1/2 FPC terminal width and can not affect the function, we judge accept. 12.2 FPC alignment hole damage \leq 1/2 alignment area and can not affect the function, we judge accept.	2.5
14	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle.13.2 No short circuits in components on PCB or FPC.	2.5 0.65



NO	Item		Criterion		AQL
NO 15	Touch Panel Chipped glass	Symbols: x: Chip length k: Seal width length L: Electrode pad leng 14.1 General glass ch 14.1.1 Chip on panel z: Chip thickness Z≦t	y: Chip width z: t: Touch Panel Total t	hickness a: LCD	
		z: Chip thickness z≤t O Unit: mm	y: Chip width ≤ 1/2 k and not over viewing area	x: Chip length x≤1/8a	

NO	Item	Criterion		AQL	
	Touch	_			2.5
16	Panel(Fish	SIZE(mm)	Acceptable Q'ty		2.5



	eye, dent	$\Phi \leq 0.2 \qquad \text{Accept no dense}$	
	and bubble on film)	$\begin{array}{ c c c c c c }\hline 0.2 < D \leq 0.4 & 5 \\ \hline 0.1 & D \leq 0.5 & 2 \\ \hline \end{array}$	
		$0.4 < D \leq 0.5$	
		0.5< D 0	
17	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$), it is acceptable.	2.5
18	Touch Panel Linearity	Less than 2.5% is acceptable.	2.5
19	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	2.5
20	General appearance	 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. 	0.65 0.65 0.65 0.65



13. Handling Precaution:

13-1 Handling of LCM

- Don't give external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance. Must not lick and swallow. when the liquid is attach to your hand, skin, cloth etc. Wash it out thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

13-2 Storage

- Store in an ambient temperature of 25±10°C, and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Storage in a clean environment, free from dust, active gas, and solvent.
- Store in anti-static electricity container.
- Store without any physical load.

13-3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: No higher than 310±10°C and less than 3 sec during Hand soldering.
- Rewiring: no more than 2 times.

14. Warranty

This product has been manufactured to specifications as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we will not take responsibility if the product is used in medical devices, nuclear power control equipment, aerospace equipment, fire and security systems, or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required. If the product is to be used in any of the above applications, we will need to enter into a separate product liability agreement.

- 1. We cannot accept responsibility for any defect arise after additional process of the product (including disassembly and reassembly), after product delivery.
- 2. We cannot accept responsibility for any defect, which may arise after the application of strong external force to the product.
- 3. We cannot accept responsibility for any defect, which may arise due to the application of static electricity after the product has passed your company's acceptance inspection procedures.
- 4. We can not accept responsibility for industrial property, which may arise through the use of your product, with exception to those issues relating directly to the structure or method of manufacturing of our product within one year from YEEBO shipment.
- 5. For Heatseal Product which required to heatseal by customer side, parts must be used within three months after delivery from factory.
- 6. For TAB Product which required to solder by customer side, parts must be used within three Module P/N: YB-TG1024600S11A-C-A0



months after delivery from factory.

7. The liability of YB is limited to repair or replacement on the terms set forth below. YB will not be responsible for any subsequent or consequential events or injury or damage to any personnel or user including third party personnel and/or user. Unless otherwise agreed in writing between YB and the customer, YB will only replace or repair any of its LCD which is found defective electrically or visually when inspected in accordance with YB GENERAL LCD INSPECTION STANDARD.

15. Guarantee:

Our products meet requirements of the environment. YEEBO ROHS requirement is based on European Union Directive 2011/65/EU(ROHS) Requirements and Update.